



Material Content Data Sheet



Halogen-Free

Sales Product Name	BFP 840ESD H6327	Issued	24. February 2022
MA#	MA000976108		
Package	PG-SOT343-4-2	Weight*	6.93 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.003	0.04		393	
	non noble metal	tin	7440-31-5	0.001	0.01		101	
	inorganic material	silicon	7440-21-3	0.024	0.34	0.39	3430	3924
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		498	
	non noble metal	chromium	7440-47-3	0.010	0.15		1493	
	non noble metal	copper	7440-50-8	3.433	49.54	49.75	495500	497591
wire	noble metal	gold	7440-57-5	0.010	0.15	0.15	1468	1468
encapsulation	organic material	carbon black	1333-86-4	0.030	0.44		4370	
	plastics	epoxy resin	-	0.651	9.40		93965	
	inorganic material	silicondioxide	60676-86-0	2.347	33.87	43.71	338713	437048
leadfinish	non noble metal	tin	7440-31-5	0.199	2.88	2.88	28755	28755
plating	noble metal	silver	7440-22-4	0.216	3.12	3.12	31214	31214
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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